

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Hisashi MAESHIMA, *et al.*

Application No.: 10/526,672

Confirmation No.: 3246

Filed: March 4, 2005

Art Unit: 1796

For: PROCESS FOR PREPARATION OF
ALICYCLIC DIEPOXY COMPOUNDS,
CURABLE EPOXY RESIN COMPOSITIONS,
EPOXY RESIN COMPOSITIONS FOR THE
ENCAPSULATION OF ELECTRONIC PARTS,
STABILIZERS FOR ELECTRICAL
INSULATING OILS, AND CASTING EPOXY
RESIN COMPOSITIONS FOR ELECTRICAL
INSULATION

Examiner: Robert SELLERS

AMENDMENT UNDER 37 CFR 1.111

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In reply to the Office Action dated December 10, 2007, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

This reply includes:

- Amendments to the specification;
- Remarks; and
- English language translation of priority document.